

# EMIF10-LCD02F3

## 10-line IPAD<sup>™</sup>, EMI filter and ESD protection for LCD and cameras

### Features

- Lead-free package
- EMI symmetrical (I/O) low-pass filter
- High efficiency in EMI filtering
- 400 µm pitch
- Compatible with high speed data rate
- Very low PCB space occupation: < 4 mm<sup>2</sup>
- Very thin package: 0.60 mm
- High efficiency in ESD suppression
- High reliability offered by monolithic integration
- High reduction of parasitic elements through integration and wafer level packaging

#### Complies with the following standards

- IEC 61000-4-2 level 4 on inputs and outputs
   15 kV (air discharge)
  - 8 kV (contact discharge)
- MIL STD 883G Method 3015-6 Class 3

### Applications

Where EMI filtering in ESD sensitive equipment is required:

- LCD for mobile phones
- Computers and printers
- Communication systems
- MCU boards

### Description

The EMIF10-LCD02F3 is a 10-line highly integrated device designed to suppress EMI/RFI noise in all systems subjected to electromagnetic interference. The EMIF10 Flip-Chip packaging means the package size is equal to the die size.

This filter includes ESD protection circuitry, which prevents damage to the protected device when subjected to ESD surges up 15 kV.











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# 1 Characteristics

#### Table 1.Absolute maximum ratings ( $T_{amb} = 25 \ ^{\circ}C$ )

Symbol	Parameter and test conditions	Value	Unit
Тj	Maximum junction temperature	125	°C
T <sub>op</sub>	Operating temperature range	-40 to +85	°C
T <sub>stg</sub>	Storage temperature range	-55 to 150	°C

#### Figure 3. Electrical characteristics (definitions)

Symbo	ol	Parameter	· · <b>↑</b> / /
V <sub>BR</sub>	=	Breakdown voltage	IPP
V <sub>CL</sub>	=	Clamping voltage	
RM	=	Leakage current @ V <sub>BM</sub>	
V <sub>RM</sub>	=	Stand-off voltage	IB
PP	=	Peak pulse current	
R	=	Breakdown current	IRM VRM VBR VCL
PP	=	Forward current	[ IR
R <sub>1/0</sub>	=	Series resistanc between input and output	
S <sub>line</sub>	=	Input capacitance per line	
			IPP

Table 2.	Electrical char	acteristics (T	<sub>mb</sub> = 25 °C)
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Symbol	Test conditions	Min.	Тур.	Max.	Unit
V <sub>BR</sub>	I <sub>R</sub> = 1 mA	6	8	10	V
I <sub>RM</sub>	V <sub>RM</sub> = 3 V		50	200	nA
R <sub>2</sub>	Tolerance ± 20%		70		Ω
C <sub>line</sub>	Vline = 0 V, $V_{OSC}$ = 30 mV, F =1 MHz			30	pF

Figure 4. S21 all lines attenuation measurement







Figure 6. ESD response to IEC 61000-4-2 Figure 7. (+15 kV air discharge) on one input and on one output

ESD response to IEC 61000-4-2 (-15 kV air discharge) on one input and on one output



Figure 8. Line capacitance versus applied voltage



# 2 Ordering information scheme

Figure 9. Ordering information scheme

EMI Filter	
Number of lines	
Information	
x = resistance value (Ohms)	
z = capacitance value / 10 (pF)	
or	
3 letters = application	
2 digits = version	
Package F = Flip Chip	



## 3 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>. ECOPACK<sup>®</sup> is an ST trademark.

Figure 10. Package dimensions









Figure 13. Flip-Chip tape and reel specification



AN1751: "EMI Filters: Recommendations and measurements"



## 4 Ordering information

#### Table 3. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF10-LCD02F3	GY	Flip-Chip	5.0 mg	5000	Tape and reel 7"

## 5 Revision history

#### Table 4.Document revision history

Date	Revision	Changes
11-Jul-2005	1	First issue.
28-Apr-2008	2	Updated ECOPACK statement. Updated <i>Figure 9, Figure 10, Figure 11</i> and <i>Figure 13</i> . Reformatted to current standards.
18-Nov-2009	3	Updated <i>Figure 10</i> for die dimension reduction. Updated <i>Figure 13</i> for scaling.



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Doc ID 11507 Rev 3

